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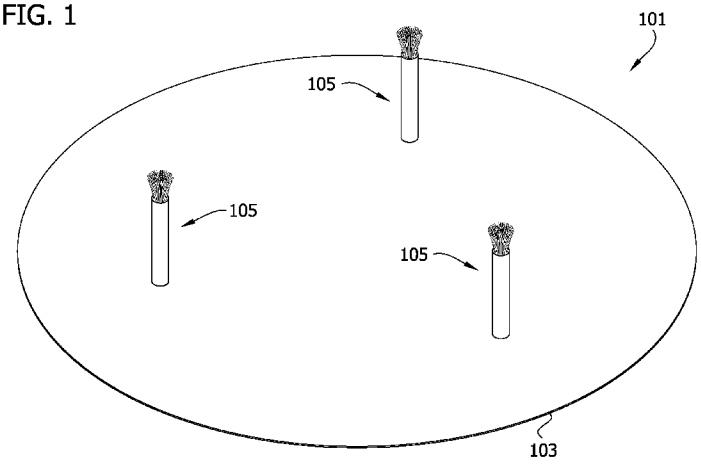
(54) Title: WAFER HOLDER FOR SUPPORTING A SEMICONDUCTOR WAFER DURING A THERMAL TREATMENT PROCESS

FIG. 1



(57) Abstract: A wafer holder for holding a semiconductor wafer during a thermal wafer treatment process. The wafer holder includes at least three wafer supports. Each wafer support includes an upright shaft and a plurality of flexible fibers supported by the shaft in positions such that at least some of the fibers engage the semiconductor wafer when the wafer rests on the wafer supports.